

Cypress Semiconductor Product Qualification Report

QTP# 024907 VERSION 1.0
June, 2003

CYWUSB6941	Wireless USB™ Radio
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CYPRESS TECHNICAL CONTACT FOR QUALIFICATION DATA:

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PRODUCT QUALIFICATION HISTORY

Qual Report	Description of Qualification Purpose	Date Comp
011406	New Product, Quad HOTLink II family, B53D-3 Technology in Fab4	Oct 01
024907	New Device , CYWUSB6941 (WirelessUSB™ Radio), B53D-3 Technology in Fab4	May 03

PRODUCT DESCRIPTION (for qualification)	
Qualification Purpose: Qualify CYWUSB6941 Device in qualified B53D-3Technology	
Marketing Part #:	CYWUSB6941
Device Description:	Wireless USB™ Radio
Cypress Division:	Cypress Semiconductor Corporation – Personal Communication Division (PCD) WA
Overall Die (or Mask) REV Level (pre-requisite for qualification):	Rev. A
What ID markings on Die:	CY7B6961A

TECHNOLOGY/FAB PROCESS DESCRIPTION – B53D-3			
Number of Metal Layers:	2	Metal Composition:	Metal 1: 500/6000/300 [Å] Metal 2: 500/6000/300 [Å]
Passivation Type and Materials:	1,000Å TEOS + 9,000Å Si ₂ N ₄		
Free Phosphorus contents in top glass layer(%):	0%		
Die Coating(s), if used:	N/A		
Number of Transistors in Device	150K		
Number of Gates in Device	30K		
Generic Process Technology/Design Rule (μ-drawn):	CMOS, 0.25 μm		
Gate Oxide Material/Thickness (MOS):	SiO ₂ / 55Å		
Name/Location of Die Fab (prime) Facility:	Cypress Minnesota, Fab4		
Die Fab Line ID/Wafer Process ID:	Fab4 / B53D-3		

ELECTRICAL TEST / FINISH DESCRIPTION	
Test Location:	CML-R
Fault Coverage:	100%

MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION	
Package Designation:	BA42
Package Outline, Type, or Name:	42-ball Thin Ball Grid Array (FBGA)
Mold Compound Name/Manufacturer:	Plaskon SMT-1N
Mold Compound Flammability Rating:	V-O per UL94
Oxygen Rating Index:	>28%
Lead Frame Designation:	N/A
Lead Frame Material:	N/A
Lead Finish, Composition / Thickness:	Solder Ball, 63% ± 5 Sn - 37% ± 5 Pb
Die Backside Preparation Method/Metallization:	Grinding
Die Separation Method:	Sawing
Die Attach Supplier:	Ablestick 8355F
Die Attach Material:	Ag
Die Attach Method:	Epoxy
Bond Diagram Designation	10-04716
Wire Bond Method:	Thermosonic
Wire Material/Size:	Au 1.0mil
Thermal Resistance Theta JA °C/W:	88 °C/W
Package Cross Section Yes/No:	N/A
Assembly Process Flow:	49-41010
Name/Location of Assembly (prime) facility:	ASE-Taiwan

PACKAGE AVAILABILITY

PACKAGE	ASSEMBLY SITE FACILITY
42-FBGA	ASE Taiwan (TAIWN-G)

Note: Please contact a Cypress Representative for other packages availability.

RELIABILITY TESTS PERFORMED PER SPECIFICATION REQUIREMENT

Stress/Test	Test Condition (Temp/Bias)	Result P/F
High Temperature Operating Life Early Failure Rate	Dynamic Operating Condition, Vcc = 3.8V, 125C	P
High Temperature Operating Life Latent Failure Rate	Dynamic Operating Condition, Vcc = 3.8V, 125C	P
Temperature Cycle	MIL-STD-883C, Method 1010, Condition C, -65°C to 150°C Precondition: JESD22 Moisture Sensitivity MSL 3 192 Hrs, 30°C/60%RH+3IR-Reflow, 220°C+5, 0°C	P
Pressure Cooker	121°C, 100%RH Precondition: JESD22 Moisture Sensitivity MSL 3 192 Hrs, 30°C/60%RH+3IR-Reflow, 220°C+5, 0°C	P
Electrostatic Discharge Human Body Model (ESD-HBM)	MIL-STD-883, Method 3015.7 (2,200V)	P
Electrostatic Discharge Charge Device Model (ESD-CDM)	Cypress Spec. 25-00020 (500V)	P
Latchup Sensitivity	±300mA, 10V In accordance with JEDEC 17. Cypress Spec. 01-00081	P

RELIABILITY FAILURE RATE SUMMARY

Stress/Test	Device Tested/ Device Hours	# Fails	Activation Energy	Thermal ³ A.F	Failure Rate ⁴
High Temperature Operating Life Early Failure Rate	1013 Devices	0	N/A	N/A	0 PPM
High Temperature Operating Life ^{1,2} Long Term Failure Rate	897,934 DHRs	0	0.7	55	20 FIT

¹ Assuming an ambient temperature of 55°C and a junction temperature rise of 15°C.

² Chi-squared 60% estimations used to calculate the failure rate.

³ Thermal Acceleration Factor is calculated from the Arrhenius equation

$$AF = \exp \left[\frac{E_A}{k} \left[\frac{1}{T_2} - \frac{1}{T_1} \right] \right]$$

where:

E_A =The Activation Energy of the defect mechanism.

k = Boltzmann's constant = 8.62×10^{-5} eV/Kelvin.

T_1 is the junction temperature of the device under stress and T_2 is the junction temperature of the device at use conditions.

Reliability Test Data

QTP #: 011406

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
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STRESS: HIGH TEMP DYNAMIC OPERTING LIFE-LATENT FAILURE RATE, 125C, 3.8V, >Vcc Max

CYP15G0401DX -BGC (7B9294A)	4048678	610111566L2	TAIWN-G	168	189	0	
CYP15G0401DX -BGC (7B9294A)	4048678	610111566L2	TAIWN-G	2097	146	0	
CYP15G0401DX -BGC (7B9294A)	4106284	610113332	TAIWN-G	168	199	0	
CYP15G0401DX -BGC (7B9294A)	4106284	610113332	TAIWN-G	2016	167	0	

Reliability Test Data

QTP #: 024907

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE (125C, 3.8V, Vcc Max)							
CY6961-BA (7B6961A)	4235189	610249040/9041	TAIWN-G	96	505	0	
CY6963-BA (7B6963A)	4235189	610246588/6591	TAIWN-G	96	250	0	
CY6963-BA (7B6963A)	4235189	610249040/6591	TAIWN-G	96	258	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE (125C, 3.8V, Vcc Max)							
CY6961-BA (7B6961A)	4235189	610249040/9041	TAIWN-G	168	245	0	
CY6961-BA (7B6961A)	4235189	610249040/9041	TAIWN-G	500	245	0	
CY6963-BA (7B6963A)	4250534	610303403/4/5	TAIWN-G	168	240	0	
CY6963-BA (7B6963A)	4250534	610303403/4/5	TAIWN-G	500	240	0	
STRESS: ESD-CHARGE DEVICE MODEL (500V)							
CY6961-BA (7B6961A)	4235189	610249040/6588	TAIWN-G	COMP	9	0	
STRESS: ESD-HUMAN BODY CIRCUIT PER MIL STD 883, METHOD 3015 (2,200V)							
CY6961-BA (7B6961A)	4235189	610249040/6588	TAIWN-G	COMP	9	0	
STRESS: STATIC LATCH-UP TESTING (125C, 10V, +/-300mA)							
CY6961-BA (7B6961A)	4235189	610249040/6588	TAIWN-G	COMP	9	0	
STRESS: PRESSURE COOKER, 121C,100%RH, PRECONDITION 192HRS 30C/60%RH, MSL3							
CY6961-BA (7B6961A)	4235189	610249040/6588	TAIWN-G	168	48	0	
CY6961-BA (7B6961A)	4235189	610249040/6588	TAIWN-G	288	46	0	
STRESS: TC COND. C -65C TO 150C, PRECONDITION 192HRS 30C/60%RH, MSL3							
CY6961-BA (7B6961A)	4235189	610249040/6588	TAIWN-G	300	48	0	
CY6961-BA (7B6961A)	4235189	610249040/6588	TAIWN-G	500	47	0	